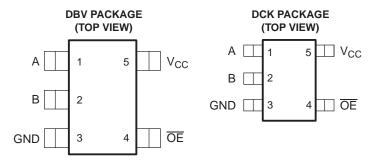


FEATURES

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The SN74CBT1G384 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{\text{OE}}$) input is high.

ORDERING INFORMATION

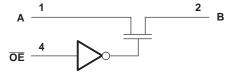
T _A	PACKA	GE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
	COT (COT 00) DDV	Reel of 3000	SN74CBT1G384DBVR	COD
40°C to 95°C	SOT (SOT-23) – DBV	Reel of 250	SN74CBT1G384DBVT	- S8D_
–40°C to 85°C	SOT (SC-70) – DCK	Reel of 3000	SN74CBT1G384DCKR	Co
		Reel of 250	SN74CBT1G384DCKT	S8_

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUT OE	FUNCTION
L	A port = B port
Н	Disconnect

LOGIC DIAGRAM (POSITIVE LOGIC)





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Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V_{CC}	Supply voltage range			-0.5	7	V
VI	Input voltage range ⁽²⁾			-0.5	7	V
	Continuous channel current				128	mA
I _{IK}	Input clamp current	V _{I/O} < 0			-50	mA
0	Deckers thermal impedence (3)	DBV package				°C/W
θ_{JA} Package thermal impedance ⁽³⁾ DBV package DCK package	DCK package			252	·C/VV	
T _{stg}	Storage temperature range			-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4	5.5	V
V_{IH}	High-level control input voltage	2		V
V_{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	-40	85	°C

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CC	NDITIONS		MIN TYP(1) MAX		
V _{IK}		V _{CC} = 4.5 V,	I _I = -18 mA				-1.2	V
I		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ
I _{CC}		$V_{CC} = 5.5 \text{ V},$	$I_{O} = 0,$	$V_I = V_{CC}$ or GND			1	μΑ
Ci	Control input	$V_I = 3 V \text{ or } 0$				3		pF
C _{io(OFF)}		$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			4		pF
		V _{CC} = 4 V,	TYP at V _{CC} = 4 V,	V _I = 2.4 V,	I _I = 15 mA	14	20	
r _{on} (2)			V ₁ = 0	$I_I = 64 \text{ mA}$		5	7	Ω
I on (2)		V _{CC} = 4.5 V	$V_1 = U$	$I_I = 30 \text{ mA}$		5	7	52
			$V_1 = 2.4 V,$	$I_I = 15 \text{ mA}$		10	15	ı

⁽¹⁾ All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

²⁾ The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

⁽²⁾ Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.



Switching Characteristics

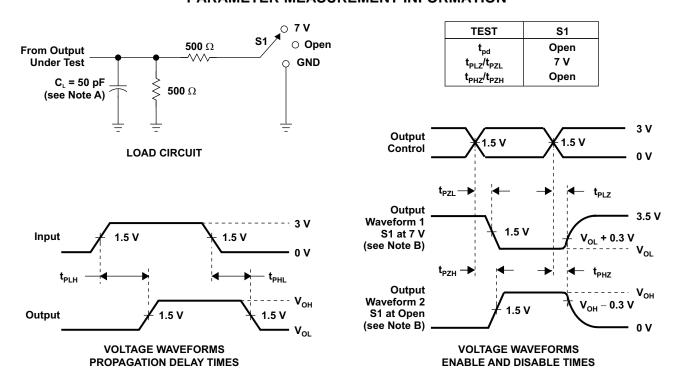
over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V	V _{CC} = 9 ± 0.5	UNIT	
	(INPUT)	(001F01)	MIN MAX	MIN	MAX	
t _{pd} ⁽¹⁾	A or B	B or A	0.35		0.25	ns
t _{en}	ŌĒ	A or B	5.5	1.6	4.9	ns
t _{dis}	ŌĒ	A or B	4.5	1	4.2	ns

⁽¹⁾ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C . All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D . The output is measured with one input transition per measurement.
- E . $\,t_{\text{PLZ}}$ and t_{PHZ} are the same as $t_{\text{dis}}.$
- H . t_{PZL} and t_{PZH} are the same as t_{en} . G . t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74CBT1G384DBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(S8DG, S8DJ, S8DR)
SN74CBT1G384DBVR.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(S8DG, S8DJ, S8DR)
SN74CBT1G384DBVT	NRND	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(S8DJ, S8DR)
SN74CBT1G384DBVT.A	NRND	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(S8DJ, S8DR)
SN74CBT1G384DCKR	NRND	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAU SN NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83, S8G, S8J, S8 R, S8U)
SN74CBT1G384DCKR.A	NRND	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83, S8G, S8J, S8 R, S8U)
SN74CBT1G384DCKT	NRND	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAU SN NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83, S8J, S8R)
SN74CBT1G384DCKT.A	NRND	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(S83, S8J, S8R)

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

NSTRUMENTS



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74CBT1G384DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74CBT1G384DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBT1G384DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74CBT1G384DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74CBT1G384DCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
SN74CBT1G384DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74CBT1G384DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT1G384DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74CBT1G384DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74CBT1G384DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74CBT1G384DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74CBT1G384DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74CBT1G384DCKR	SC70	DCK	5	3000	203.0	203.0	35.0
SN74CBT1G384DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74CBT1G384DCKT	SC70	DCK	5	250	202.0	201.0	28.0





NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.5. Lead width does not comply with JEDEC.
- 6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side





NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 10. Board assembly site may have different recommendations for stencil design.







NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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